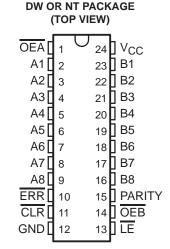
## SN74BCT29853 8-BIT TO 9-BIT PARITY BUS TRANSCEIVER

SCBS002D - SEPTEMBER 1987 - REVISED APRIL 1994

- BiCMOS Process With TTL Inputs and Outputs
- State-of-the-Art BiCMOS Design Significantly Reduces Standby Current
- Flow-Through Pinout (All Inputs on Opposite Side From Outputs)
- Functionally Equivalent to AMD Am29853
- High-Speed Bus Transceiver With Parity Generator/Checker
- Parity-Error Flag With Open-Collector Output
- Latch for Storage of the Parity-Error Flag
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (NT)



### description

The SN74BCT29853 is an 8-bit to 9-bit parity transceiver designed for asynchronous communication between data buses. When data is transmitted from the A to B bus, a parity bit is generated. When data is transmitted from the B to A bus with its corresponding parity bit, the parity-error (ERR) output will indicate whether or not an error in the B data has occurred. The output-enable (OEA, OEB) inputs can be used to disable the device so that the buses are effectively isolated.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with an open-collector parity-erro  $(\overline{ERR})$ r flag.  $\overline{ERR}$  can be either passed, sampled, stored, or cleared from the latch using the latch-enable  $(\overline{LE})$  and clear  $(\overline{CLR})$  control inputs. When both  $\overline{OEA}$  and  $\overline{OEB}$  are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition which gives the designer more system diagnostic capability. The SN74BCT29853 provides true logic.

The SN74BCT29853 is characterized for operation from 0°C to 70°C.

#### **FUNCTION TABLE**

		ı	INPUTS				OUTP	UT AND I/O	١		
OEB	OEA	CLR	LE	Ai ∑ of H's	Bi† ∑ of H's	Α	В	PARITY	ERR‡	FUNCTION	
L	Н	Х	Х	Odd Even	NA	NA	Α	L H	NA	A data to B bus and generate parity	
Н	L	Х	L	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity	
Н	L	Н	Н	NA	Х	Χ	NA	NA	N-1	Store error flag	
Х	Χ	L	Н	Χ	Χ	Χ	NA	NA	Н	Clear error-flag register	
Н	Н	H L X X	H H L	X X L Odd H Even	Х	Z	Z	Z	NC H H L	Isolation§ (parity check)	
L	L	Х	Х	Odd Even	NA	NA	А	H L	NA	A data to B bus and generate inverted parity	

NA = not applicable, NC = no change, X = don't care

<sup>§</sup> In this mode, the ERR output, when enabled, shows inverted parity of the A bus.

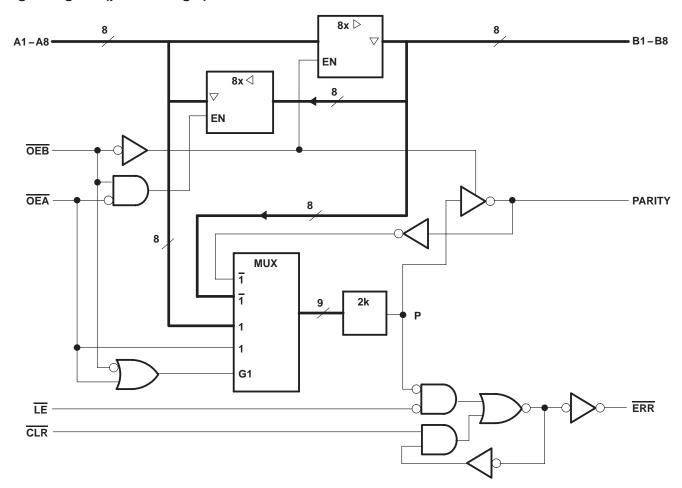


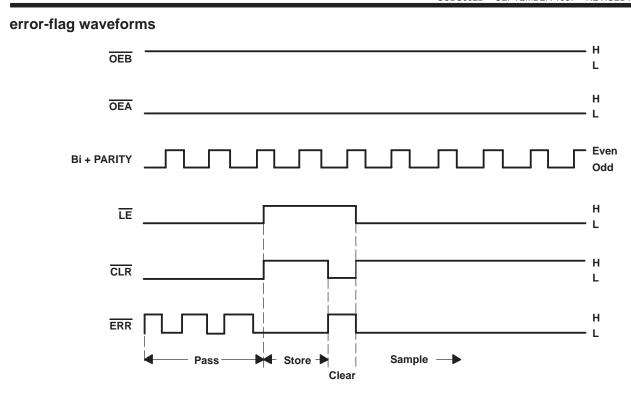
<sup>†</sup>Summation of high-level inputs includes PARITY along with Bi inputs.

<sup>‡</sup> Output states shown assume the ERR output was previously high.

SCBS002D - SEPTEMBER 1987 - REVISED APRIL 1994

# logic diagram (positive logic)





### **ERROR-FLAG FUNCTION TABLE**

INP	UTS	INTERNAL TO DEVICE	OUTPUT PRESTATE	OUTPUT	FUNCTION
LE	CLR	POINT P ERR <sub>n-1</sub> † ERR			
L	L	L H	Х	L H	Pass
L	Н	L X H	X L H	L L H	Sample
Н	L	Х	Х	Н	Clear
Н	Н	Х	L H	L H	Store

<sup>†</sup> ERR<sub>n-1</sub> represents the state of the ERR output before any changes at CLR, LE, or point P.

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	 7 V
Input voltage, V <sub>I</sub>	 7 V
Operating free-air temperature range	 0°C to 70°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## SN74BCT29853 8-BIT TO 9-BIT PARITY BUS TRANSCEIVER

SCBS002D - SEPTEMBER 1987 - REVISED APRIL 1994

### recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	V
$V_{IH}$	High-level input voltage		2			V
$V_{IL}$	Low-level input voltage				0.8	V
Vон	High-level output voltage	RR			2.4	V
loh	High-level output current				-24	mA
loL	Low-level output current				48	mA
TA	Operating free-air temperature		0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	T	EST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2	V
.,	All inputs (sutputs susent EDD	V 45V	$I_{OH} = -15 \text{ mA}$	2.4			.,
VOH	All inputs/outputs except ERR	V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			V
loH	ERR	$V_{CC} = 4.5 \text{ V},$	V <sub>OH</sub> = 2.4 V			20	μΑ
V <sub>OL</sub>		$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 48 \text{ mA}$		0.35	0.5	V
Ц		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			0.1	mA
I <sub>IH</sub> ‡		$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20	μΑ
Data		V 55V	V 0.4V			-0.2	A
I <sub>IL</sub> ‡	Control	$V_{CC} = 5.5 \text{ V},$	$V_I = 0.4 V$			-0.75	mA
los§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0	-75		-250	mA
ICCL		$V_{CC} = 5.5 \text{ V},$	Outputs open		55	80	mA
ICCZ		V <sub>CC</sub> = 5.5 V,	Outputs open		30	45	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			MIN	MAX	UNIT
	Dulas duration	LE low	10		
ι <sub>W</sub>	Pulse duration	CLR low	10	ns	
t <sub>su</sub>	Setup time before LE↓	Bi and PARITY	18		ns
th	Hold time after LE↓	Bi and PARITY	8		ns

<sup>&</sup>lt;sup>‡</sup> These parameters include off-state output current for I/O ports only.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

## SN74BCT29853 8-BIT TO 9-BIT PARITY BUS TRANSCEIVER

SCBS002D - SEPTEMBER 1987 - REVISED APRIL 1994

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Note 1)

PARAMETER	FROM	TO	V <sub>C</sub>	C = 5 V, = 25°C		MIN	MAX	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX			
<sup>t</sup> PLH	A on D	D on A	1	5	7	1	10	
t <sub>PHL</sub>	A or B	B or A	1	5	7	1	10	ns
<sup>t</sup> PLH	^	DADITY	1.5	10	13	1.5	15	
t <sub>PHL</sub>	А	PARITY	1.5	10	13	1.5	15	ns
<sup>t</sup> PZH	OEA or OEB	A D	2	13	16	2	20	ns
t <sub>PZL</sub>	OEA OI OEB	A or B	2	13	16	2	20	
<sup>t</sup> PHZ	OEA or OEB	A D	2	13	16	2	20	ns
tpLZ	OEA OF OEB	A or B	2	13	16	2	20	
<sup>t</sup> PLH	CLR	ERR	1.5	11	14	1.5	15	
t <sub>PHL</sub>	LE	EKK	1.5	5	7	1.5	9	ns
<sup>t</sup> PLH	<del></del> OEA	DADITY	1.5	10	13	1.5	15	
<sup>t</sup> PHL	OEA	PARITY	1.5	10	13	1.5	15	ns
t <sub>PLH</sub>	Bi/PARITY	ERR	1.5	17	22	1.5	24	ns l
<sup>t</sup> PHL	DI/ FARITT	EKK	1.5	10	13	1.5	16	

NOTE 1: Load circuits and voltage waveforms are shown in Section 1.



## PACKAGE OPTION ADDENDUM

11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
SN74BCT29853DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74BCT29853DWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74BCT29853NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

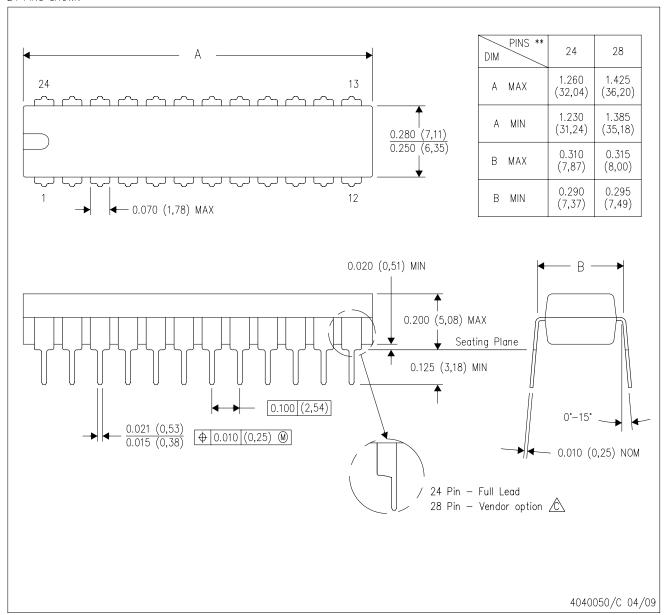
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

# NT (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

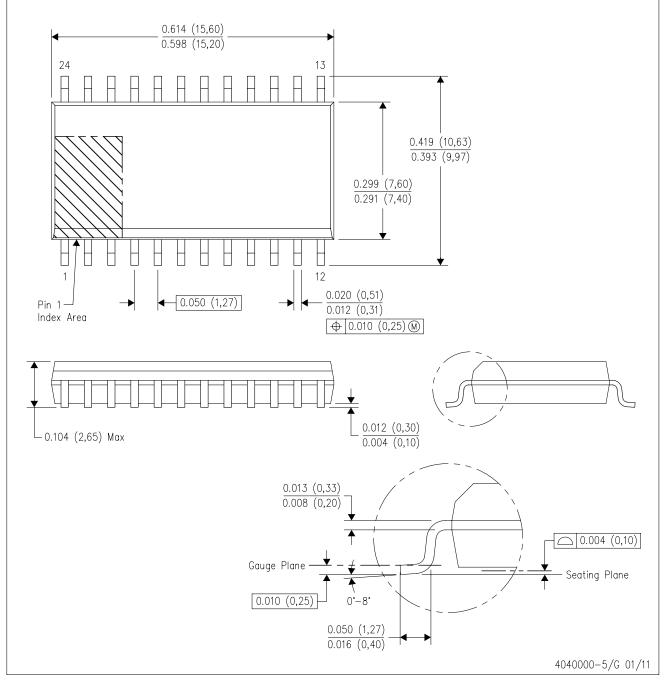
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Products	Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors <a href="https://www.ti.com/omap">www.ti.com/omap</a> TI E2E Community <a href="https://example.com/omap">e2e.ti.com/omap</a>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>